

EPCDESIGNTOOL_LG-EM

Mechanical Die for Electromigration Testing

EPCDESIGNTOOL_LG-EM are sized equivalent to EPC device [EPC2001C](#) with die size 4.1 mm x 1.6 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

Figure 1: Die Photo for EPCDESIGNTOOL_LG-EM

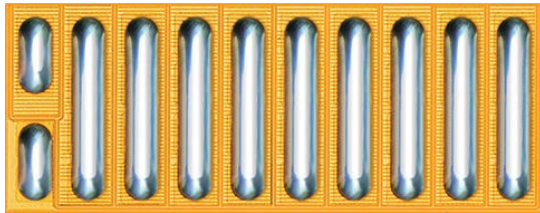
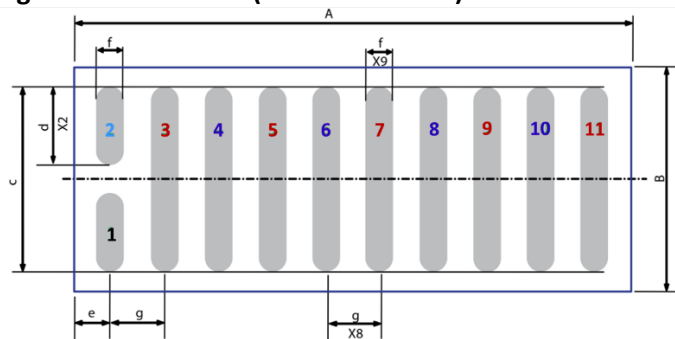


Figure 2: Die Outline (Solder Bar View)



| DIM | MICROMETERS | | |
|-----|-------------|---------|------|
| | MIN | Nominal | MAX |
| A | 4075 | 4105 | 4135 |
| B | 1602 | 1632 | 1662 |
| c | 1379 | 1382 | 1385 |
| d | 577 | 580 | 583 |
| e | 235 | 250 | 265 |
| f | 195 | 200 | 205 |
| g | 400 | 400 | 400 |

Pad 1 is Gate;

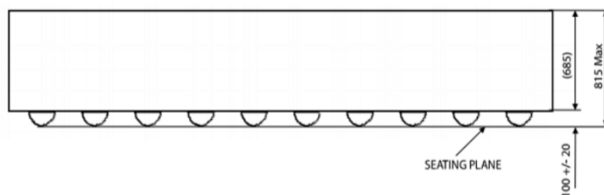
Pads 3, 5, 7, 9, 11 are Drain

Pads 4, 6, 8, 10 are Source

Pad 2 is Substrate

NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor

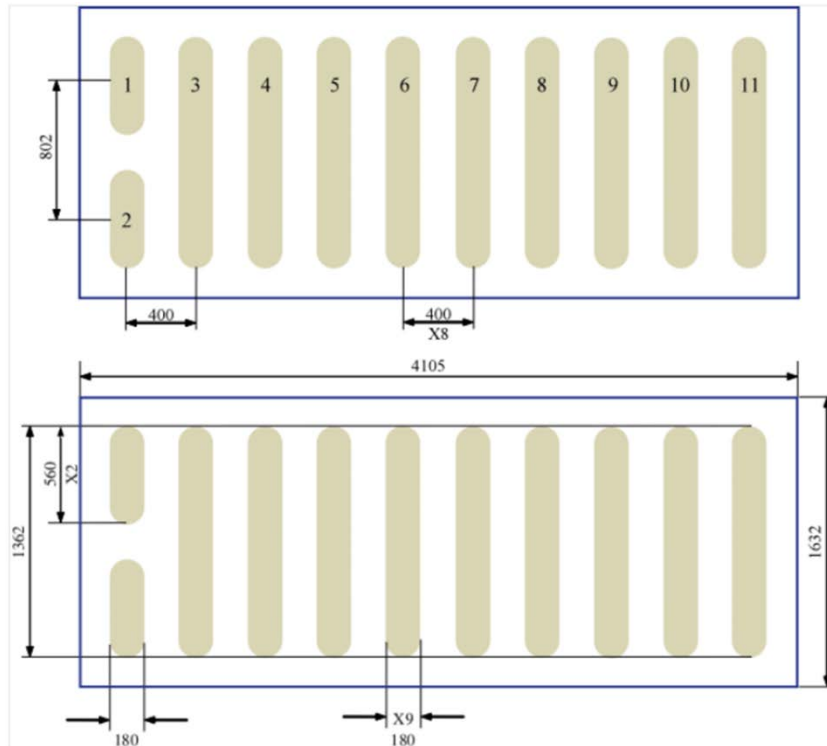
Figure 3: Side View



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Figure 4: Recommended Land Pattern (units in μm)

Land pattern is solder mask defined. Solder mask opening is $180\ \mu\text{m}$. Recommended stencil should be 4mil ($100\ \mu\text{m}$) thick, must be laser cut, Stencil opening can be per the bump drawing.



Pad 1 is Gate;

Pads 3, 5, 7, 9, 11 are Drain

Pads 4, 6, 8, 10 are Source

Pad 2 is Substrate

Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyBasics.aspx

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